

Tool ID: 308  
Tool Location: 107

Equipment Information Sheet  
OEM Endeavor M1

Manager: Tom Pennell  
Backup: Mac McMurdy

607-254-4309  
607-254-4813

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during operation.

USAGE RESTRICTIONS

- No buddy system required.

SCHEDULING/SIGN-UP RESTRICTIONS

- Maximum 4 hr block reservations anytime - Must leave a 4hr block between reservations
- Maximum 12 hours reserved in advance at any time.

Minimum Tool Time: 30 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 2: Silicon Based Substrates and Select Refractory Metals	
Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO <sub>2</sub> substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dielectric films	No High Vapor pressure materials
CNF Refractory Metals (ie Al, Ti,Ta,W,Pt,Mo,Cr,Ni)	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- CMOS compatible metals only at this time.
- Adhesives are not allowed (scotch tape, Kapton tape, glues, epoxies, greases, etc are not allowed) in the chamber. Only use clips to secure substrates.

Last Updated: 07/21/2020